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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/681,643	05/15/2001	Takatoshi Tsujimura	JP920000112US1	8744
35060	7590	01/21/2005	EXAMINER	
THE LAW OFFICE OF IDO TUCHMAN 69-60 108ST., SUITE 503 FOREST HILLS, NY 11375			COLEMAN, WILLIAM D	
			ART UNIT	PAPER NUMBER
			2823	

DATE MAILED: 01/21/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/681,643

Applicant(s)

TSUJIMURA ET AL.

Examiner

W. David Coleman

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 30 July 2004.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-10 and 19-21 is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-10 and 19-21 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☐ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____.

DETAILED ACTION***Continued Examination Under 37 CFR 1.114***

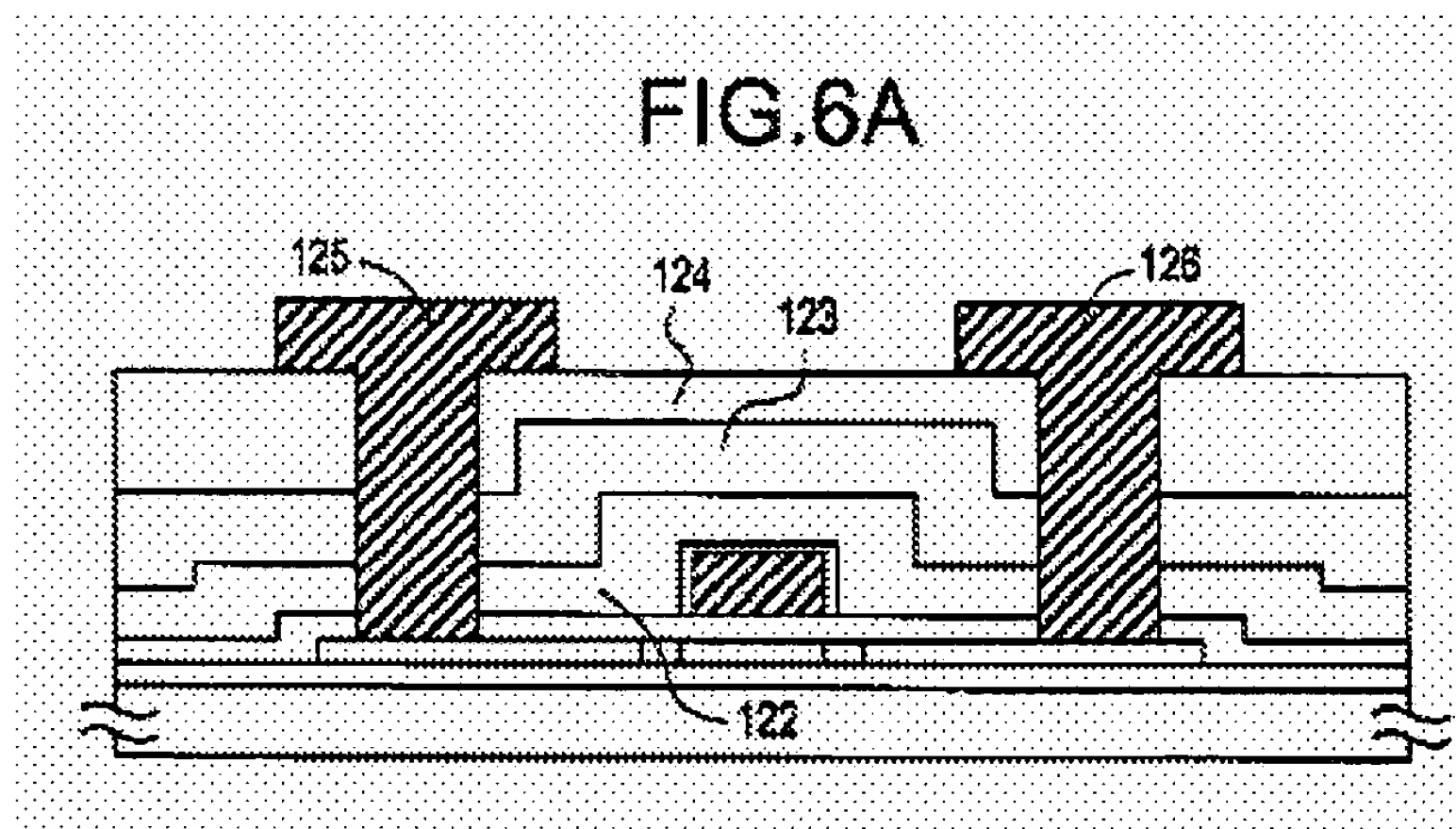
1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on July 30, 2004 has been entered.

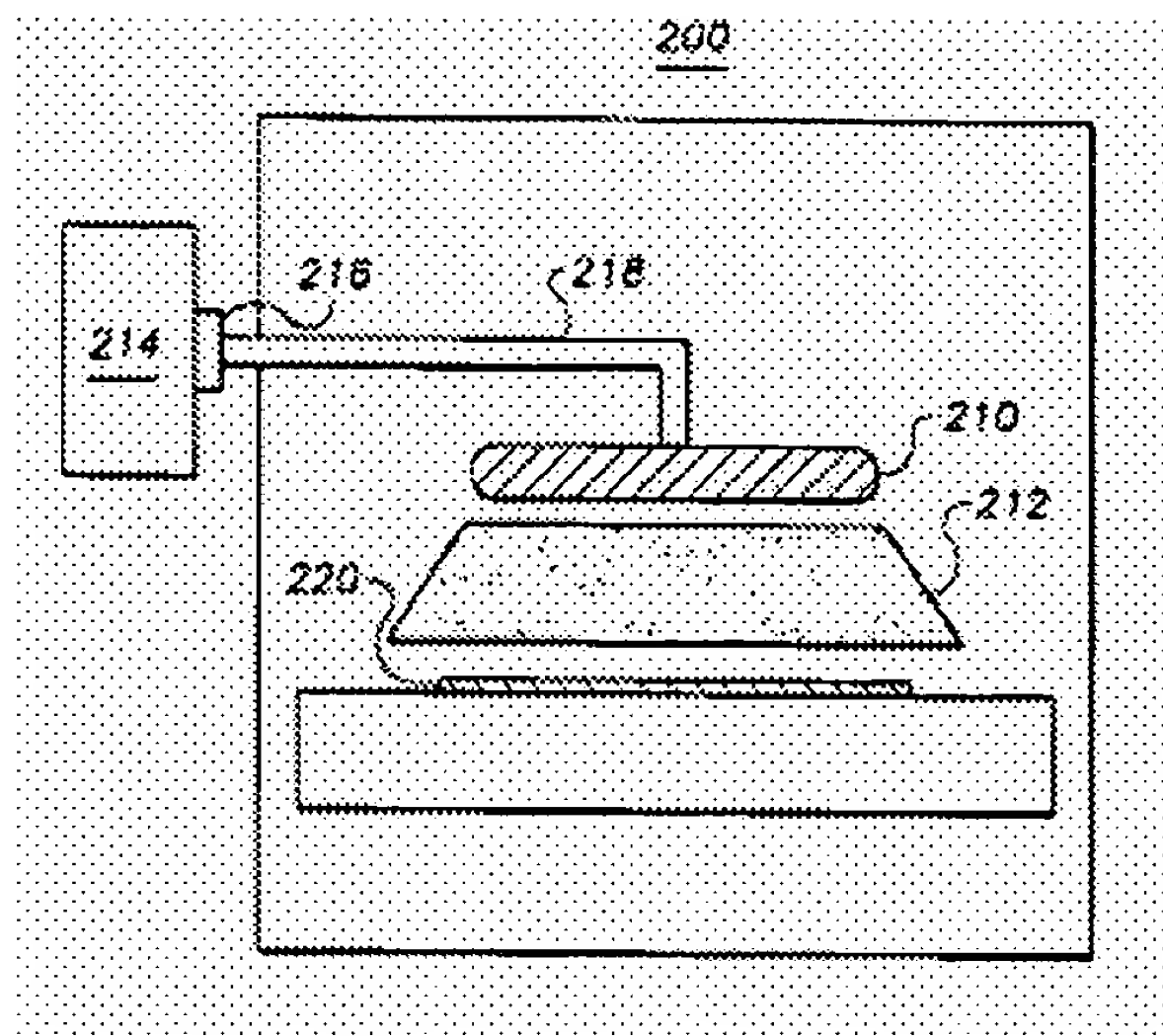
Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1-10 and 19-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ohnuma et al., U.S. Patent 6,072,193 in view of Gardner et al., U.S. Patent 6,066,519.





3. Pertaining to claims 1 and 2, Ohnuma discloses a semiconductor process substantially as claimed. See **FIGS. 1A-2D**, where Ohnuma teaches a manufacturing method of an active matrix device (column 17, line 62) including a top gate type TFT, which comprises a process of forming the top gate type TFT, wherein the process of forming the top gate type TFT includes the steps of:

arranging a substrate **101** having source **125** and drain electrodes **126** formed therein in the processing chamber; doping the source and drain electrodes with P (phosphorous), (column 3, lines 51-54); and forming an a-Si layer **103** and a gate insulating film **104** in the processing chamber; and

wherein forming the oxide film on the inner wall of the CVD processing chamber is performed before doping the source and drain electrodes with P. However, Ohnuma fails to disclose forming an oxide film on an inner wall of a CVD processing chamber. Gardner teaches forming an oxide on an inner wall of a CVD processing chamber (column 6, lines 8-14). In view of

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Gardner, it would have been obvious to one of ordinary skill in the art because when forming a gate dielectric residual oxide forms on the chamber walls (column 6, lines 10-12).

4. Pertaining to claim 2, Ohnuma fails to disclose removing the oxide film from the inner wall after the step of forming the a-Si layer and the gate insulating layer. Gardner teaches the step of removing oxide between runs. In view Gardner, it would have been obvious to one of ordinary skill in the art to remove oxide from the chamber walls after the step of forming the a-Si layer and the gate insulating film because the a silicon gate dielectric layer may be formed in a highly controlled manner (column 6, lines 21-23).

5. Pertaining to claim 3, Ohnuma teaches a manufacturing method of an active matrix device according to claim 1,

wherein the oxide film contains SiO_x.

6. Pertaining to claim 4, Ohnuma teaches a manufacturing method of an active matrix device according to claim 1, wherein the active matrix device is a liquid crystal display (column 17, line 62).

7. Pertaining to claim 5, Ohnuma teaches a manufacturing method of an active matrix device according to claim 1, wherein the active matrix device is an electroluminescence display (column 17, line 62).

8. Pertaining to claim 6, Ohnuma teaches a manufacturing method of an active matrix device according to claim 2, wherein the oxide film contains SiO_x.

9. Pertaining to claim 7, Ohnuma teaches a manufacturing method of an active matrix device according to claim 2, wherein the active matrix device is a liquid crystal display.

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10. Pertaining to claim 8, Ohnuma teaches a manufacturing method of an active matrix device according to claim 3, wherein the active matrix device is a liquid crystal display.

11. Pertaining to claim 9, Ohnuma teaches a manufacturing method of an active matrix device according to claim 2, wherein the active matrix device is an electroluminescence display.

12. Pertaining to claim 10, Ohnuma teaches a manufacturing method of an active matrix device according to claim 3, wherein the active matrix device is an electroluminescence display.

13. Pertaining to claim 17, Ohnuma in view of Gardner teaches a manufacturing method of an active matrix device according to claim 1, further comprising heating the inner wall of the CVD processing chamber. Gardner discloses outgassing the oxide and controlling the temperature of the of the chamber (column 3, lines 22-40).

14. Pertaining to claim 18, Ohnuma teaches a manufacturing method of an active matrix device according to claim 1, wherein the oxide film is selected from the group of SiO_x

15. Pertaining to claim 19, Ohnuma teaches a manufacturing method of an active matrix device including a top gate TFT, which comprises a process of forming the top gate TFT, wherein the process of forming the top gate TFT includes the steps of:

forming an oxide film on **102/109** on a substrate **101** (please note that the Examiner takes the position that oxide film formation is well known to incorporate in forming a TFT);
arranging a substrate **101** having source and drain electrodes formed therein in the processing chamber;
doping the source and drain electrodes with P;
forming an a-Si layer and a gate insulating film in the processing chamber; and

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the gate oxide is formed before doping the source and drain electrodes with P (phosphorus).

However, Ohnuma fails to disclose that during the formation of the oxide layer on the substrate, oxide formation occurs on the CVD processing chamber with a film of any thickness including at least 50 nm in thickness. Gardner teaches forming an oxide on an inner wall of a CVD processing chamber (column 6, lines 8-14). In view of Gardner, it would have been obvious to one of ordinary skill in the art because when forming a gate dielectric residual oxide forms on the chamber walls (column 6, lines 10-12).

16. Pertaining to claim 20, the combined teachings discloses a manufacturing method of an active matrix device according to claim 19, wherein the oxide is approximately 100 nm (column 7, lines 9-10).

17. Pertaining to claim 21, Ohnuma in view of Gardner discloses a manufacturing method of an active matrix device according to claim 19, wherein forming the oxide film on the inner wall of the CVD chamber is performed before doping the source and drain electrodes with P (please see the rejection as applied to claim 1 above).

Conclusion

18. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 571-272-1856. The examiner can normally be reached on 9:00 AM-5:00 PM.

19. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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20. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



W. David Coleman
Primary Examiner
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WDC